

FEATURES:

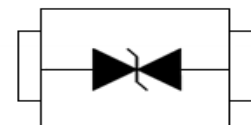
- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Low operating voltage: 5V
- ✧ ROHS compliant



SOD-323

MAIN APPLICATIONS

- ✧ Cell Phone Handsets and Accessories
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Pagers
- ✧ Microprocessor based equipment



PIN Configuration

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)

MECHANICAL CHARACTERISTICS

- ✧ Package SOD-323
- ✧ Molding Compound Flammability Rating : UL 94V-O
- ✧ Quantity Per Reel : 3,000pcs
- ✧ Lead Finish : Lead Free
- ✧ Marking code: 05B

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T_{stg}	-55 to +150	$^\circ\text{C}$
Operating junction temperature range	T_j	-55 to +125	$^\circ\text{C}$
Lead Soldering Temperature	T_L	260 (10 sec.)	$^\circ\text{C}$
Peak pulse power dissipation on 8/20 μs waveform	P_{PP}	450	W
ESD per IEC 61000-4-2 (Air)	V_{ESD}	+/- 30	kV
ESD per IEC 61000-4-2 (Contact)		+/- 30	

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Reverse Working Voltage	V_R				5	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1\text{mA}$	6.0	7.0	8.0	V
Reverse Leakage Current	I_R	$V_R = 5\text{V}$			10	μA
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu\text{s}$			30	A
Clamping Voltage	V_C	$I_{PP} = 30\text{A}$, $t_p = 8/20\mu\text{s}$			15	V
Junction Capacitance	C_J	$V_R = 0\text{V}$, $f = 1\text{MHz}$		60	100	pF

RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^\circ\text{C}$, unless otherwise noted)

FIG.1: V- I curve characteristics (Bi-directional)

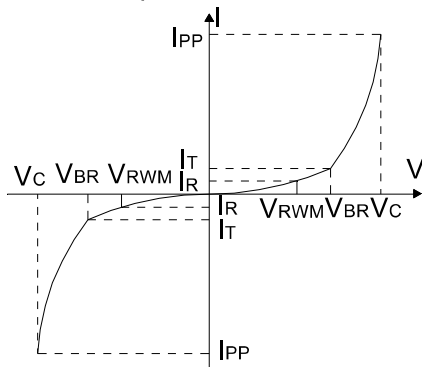


FIG.2: Pulse waveform (8/20 μs)

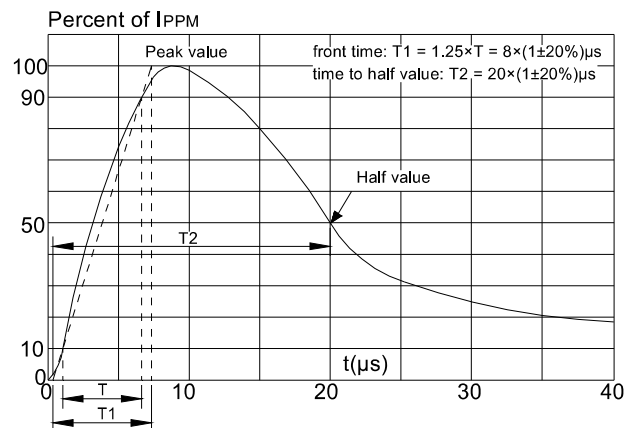


FIG.3: Pulse derating curve

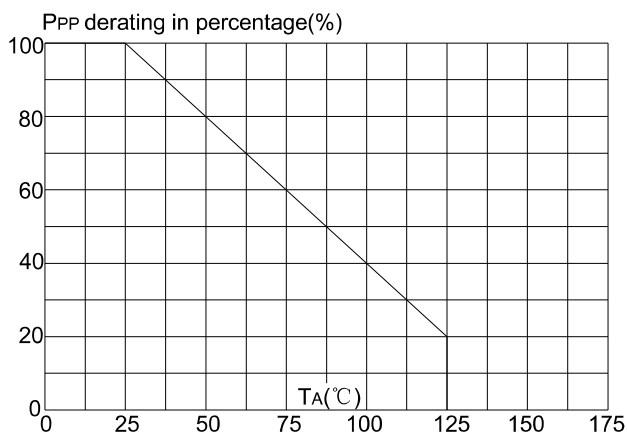
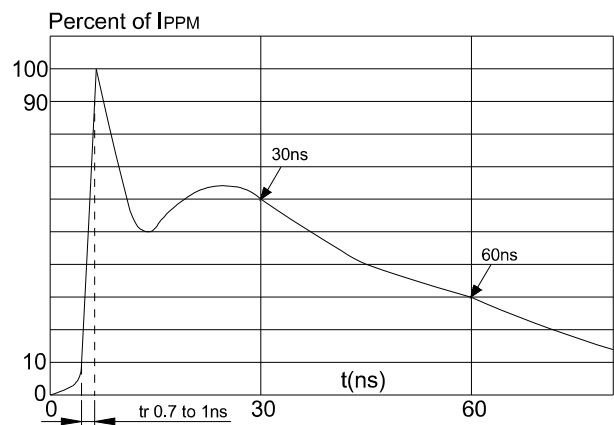
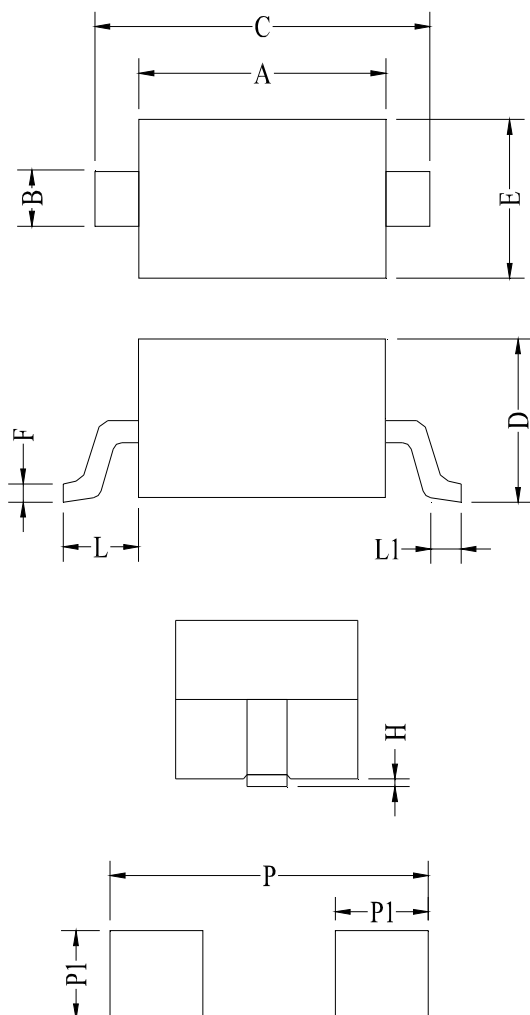


FIG.4: ESD clamping



PACKAGE MECHANICAL DATA

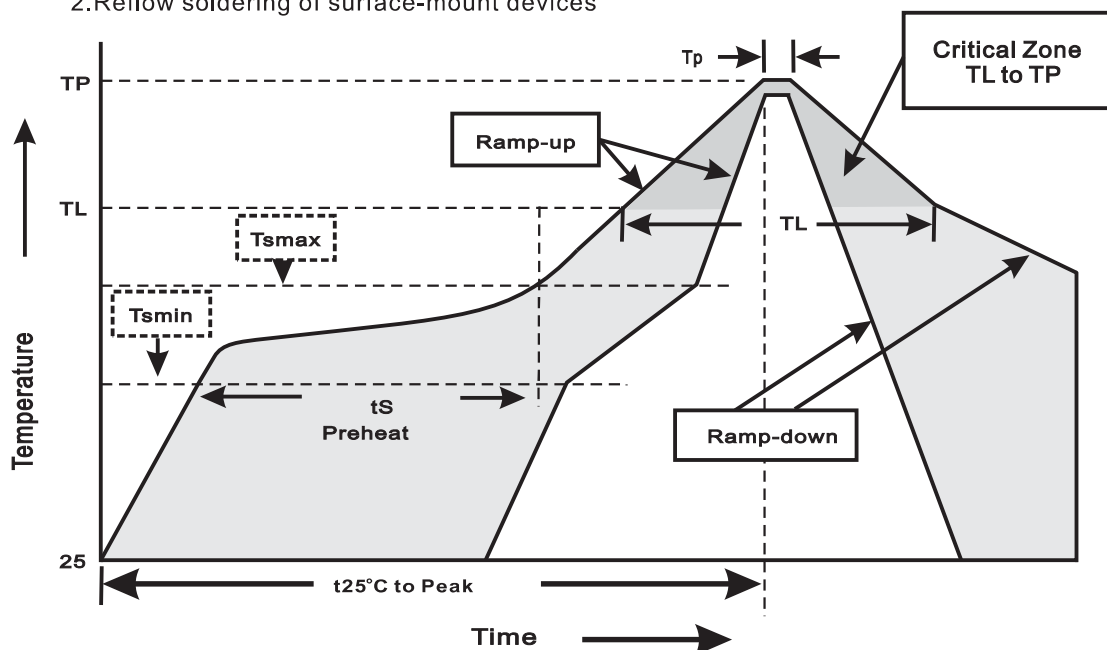


Symbol	Millimeter		Inches	
	Min	Max	Min	Max
A	1.60	1.80	0.063	0.071
B	0.25	0.35	0.010	0.014
C	2.50	2.70	0.098	0.106
D	0.00	1.00	0.000	0.039
E	1.20	1.40	0.047	0.055
F	0.08	0.15	0.003	0.006
L	0.475REF		0.019REF	
L1	0.25	0.40	0.010	0.016
H	0.00	0.10	0.000	0.004
P	3.00		0.118	
P1	0.80		0.031	

Land Pattern

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$